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Insulating Gap Filler

exhibits a thermal conductivity of 7.0W/mK

The silicone gap-filler TGF-Y-SI features a very low thermal resistance and an excellent elasticity for filling air gaps in a variety of electronic designs, while maintaining a dielectric insulation of over 10kV/mm. Aimed at cooling high-end CPUs, the soft and shock-absorbing sheet is tacky on one of its sides to allow for easy handling. Tailor-made parts can be cut out from 200x200mm sheets in thicknesses of 0.50,



1.0 and 2.0mm. Other features include an excellent chemical resistance and long-term stability for operation in a temperature range of -40 to +200°C. The product is residue-free after removal.

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